MKP Film Capacitor

Material Data Sheet

Product Class	**B25620Cx**
Date	**28/06/2022**
IMDS ID if available	**NA**
Version	**5.02.1a (03/2019)**

Product Part (IMDS: semi component)	**Material Class** (IMDS: Material)	**Material (Classification)** VDA 231	**Substance**	TMPS**) [wt%]	**CAS if applicable**	**typical mass of material [wt-%]**	**Traces see 1)**
Active Part	Thermoplastic	2A	Polypropylene (PP)	100	9003-07-0	51.25	
	Heavy Metals	1C	Zinc (Zn)	100	7440-66-6	5.63	
	Thermoplastic	2A	Polybutylene terephthalate (PBT)	70	26062-94-2	2.33	
	Mineral Materials	3A	Fiber Glass	30	65997-17-3		
Encapsulation	Thermoplastic	2A	Polybutylene terephthalate (PBT)	70	26062-94-2	4.66	
	Mineral Materials	3A	Fiber Glass	30	65997-17-3		
	Thermoplastic	2A	Polypropylene (PP)	100	9003-07-0	0.87	
	Light Metals	1B	Aluminum (Al)	100	7429-90-5	12.23	
	Duromer	2D	Polyurethane (PU)	100	9009-54-5	10.29	
	Paper, Cardboard	6D	Cellulose	100	9004-34-6	0.78	
	Iron and Steel	1A	Steel	100	65997-19-5	1.75	
	Elastomer	2B	Nitrile Rubber	100	9005-98-5	0.29	
	Thermoplastic	2A	Polyamide (PA)	46	25038-54-4	2.93	
	Mineral Materials	3A	Fiber Glass	30	65997-17-3		
	Organic, solid	4B	Bromine compound (Br)	24	7726-95-6		
Termination	Heavy Metals	1C	Brass(alloy)	97	86376-49-0	2.72	
	Heavy Metals	1C15	Lead (Pb)	3	7439-92-1		
	Heavy Metals	1C11	Copper (Cu)	100	7440-50-8	2.52	
	Heavy Metals	1C8	Tin (Sn)	100	7440-31-5	1.07	
	Thermoplastic	2A	Polyolefin	100	308070-21-5	0.68	
					Sum in total:	100	

Sizes D x H [mm.]	weight range [kg]	Sizes D x H [mm.]	weight range [kg]	Sizes D x H [mm.]	weight range [kg]	Sizes D x H [mm.]	weight range [kg]	part numbers B25620Cx
85x74	0.48	85x159	1.03	116x99	1.17	116x227	2.60	
85x99	0.61	85x177	1.13	116x124	1.44	116x252	2.89	
85x124	0.74	85x227	1.43	116x136	1.59	116x267	3.04	
85x136	0.87	85x252	1.63	116x159	1.89	116x277	3.17	
85x139	0.89	116x74	0.92	116x177	2.09	116x349	3.99	

Not Part of a Product Class

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*) others: .(not declarable or prohibited substances acc. GADSL)

**) typical mass percentage of substance

Important remarks:

1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated.

2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK Electronics AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (☑ valid ☐ not valid **)**

☐ **no exemptions;**

☐ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

☐ Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;

☑ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

☐ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

☐ Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

☐ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;

☐ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

☐ Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

☐ Other Exemption than above .....

